

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

1. (Currently Amended) Method for soldering an object comprising several soldered joints, which method comprises the steps of:

- mechanically soldering of at least some of the soldered joints;
- visually assessing the soldered joints; and
- correctively soldering the visually assessed soldered joints that do not meet relevant quality requirements; wherein the corrective soldering is carried out with a selective soldering device,

wherein said visual assessment takes place by means of a video camera and a computing device connected to the video camera, wherein the assessment criteria for the soldered joints are stored in the computing device, and wherein the corrective soldering of the soldered joints is carried out with a different soldering device as the mechanical soldering.

2. (Previously Presented) Method according to claim 1, wherein said corrective soldering of the soldered joints that do not meet the requirements takes place automatically under the control of the computing device.

3. (Canceled)

4. (Canceled)

5. (Previously Presented) Method according to claim 1, wherein said transport takes place by means of a robot.

6. (Previously Presented) Method according to claim 1, wherein said apparatus is suitable for soldering printed circuit boards.

7. (Currently Amended) Apparatus for soldering objects comprising several soldered

joints, which apparatus comprises:

- a conveyor for supplying the objects to be soldered and discharging the soldered objects;
- a mechanical soldering device for soldering the objects to be soldered, wherein the mechanical soldering device is a wave soldering device;
- a video camera for recording at least one image of at least some of the soldered joints made by the soldering device;
- a computing device connected to the video camera for receiving from the video camera signals representing images recorded by the video camera, said computing device being arranged for comparing said signals with signals that are representative of correct soldered joints; and
- a corrective soldering device for the corrective soldering of soldered joints that have been found not to meet the criteria that are stored in the computing device; wherein the corrective soldering device is a selective soldering device.

8. (Canceled)

9. (Previously Presented) Apparatus according to claim 7, wherein said corrective soldering device is arranged for the corrective soldering of only those soldered joints that have been found not to meet the criteria.

10. (Canceled)

11. (Previously Presented) Apparatus according to claim 7, further comprising a handling device for carrying out the following operations under the control of the computing device:

- moving the objects to be soldered from the conveyor to the soldering device;
- moving the soldered objects from the soldering device to a position within the recording area of the video camera;
- moving the soldered objects from the recording area of the video camera to the conveyor; and

- moving the soldered objects from the video camera to and from the corrective soldering device, if the image recorded by the video camera does not meet the criteria that are stored in the computing device.

12. (Previously Presented) Apparatus according to claim 11, wherein said handling device is a robot controlled by the computing device.

13. (Previously Presented) Apparatus according to claim 7, wherein the apparatus is suitable for handling printed circuit boards.

14. (Previously Presented) Apparatus according to claim 7, wherein said corrective soldering device is arranged for soldering only a single soldered joint or a single group of soldered joints under the control of the computing device.

15. (Canceled)

16. (Previously Presented) Apparatus according to claim 14, wherein said handling device is suitable for exchanging masking plates under the control of the computing device.

17. (Canceled)

18. (Currently Amended) Method ~~of~~ according to claim 17, wherein the mechanical soldering is carried out with a wave soldering device.

19. (Currently Amended) ~~Apparatus~~ Method according to claim ~~7~~ 1, wherein ~~said the~~ mechanical soldering ~~device is~~ carried out with a selective soldering device.

20. (Canceled)

21. (Canceled)